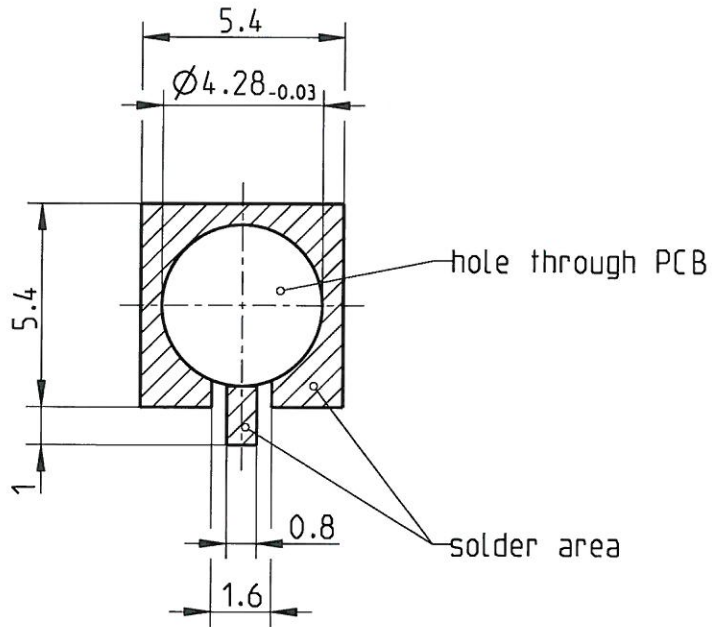


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Leiterplatten-Layout
 PCB layout
 B 229



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formblatt: TLC-FB-05-PE-AL-Einzelteil
 Platz: 13/09-01/09/01/01/01/01
 Datum: 23.07.2007
 Version: 1.2

Dimensions in mm



ISO-Projektion Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		scale: 5:1	weight(g): surface(mm ²):				
				material:							
				date	name	Leiterplatten-Layout PCB layout					
				drawn	23.07.2007			A_Nobis			
				check.	24.7.07			[Signature]			
				appr.	29.07.07			[Signature]			
dimensioning incl. finish						drawing-no...: MB_229					
a00	07-0538	A_Nobis	23.07.2007	distribu-	FE	AZ	QSM	RMT	.	sheet: 1 of: 1	
rev.	change-no	name	date	tion to:	X		